

**CLAIM AMENDMENTS:**

Claim 1 (canceled).

Claim 2 (Currently Amended): A semiconductor device, ~~according to claim 1~~,  
comprising:

a substrate;

a semiconductor chip having one surface bonded to a surface of the  
substrate; and

a warp preventing sheet bonded to and entirely covering the other surface  
of the semiconductor chip, wherein

end surfaces of the warp preventing sheet are flush with corresponding  
end surfaces of the semiconductor chip, wherein the warp preventing sheet has a  
coefficient of elasticity substantially equal to that of the substrate.

Claim 3 (Currently Amended): A semiconductor device, ~~according to claim 1~~,  
comprising:

a substrate;

a semiconductor chip having one surface bonded to a surface of the  
substrate; and

a warp preventing sheet bonded to and entirely covering the other  
surface of the semiconductor chip, wherein

end surfaces of the warp preventing sheet are flush with corresponding  
end surfaces of the semiconductor chip, wherein the warp preventing sheet has a  
coefficient of thermal expansion substantially equal to that of the substrate.

Claim 4 (Currently Amended): A semiconductor device, ~~according to claim 1,~~  
comprising:

a substrate;  
a semiconductor chip having one surface bonded to a surface of the  
substrate; and

a warp preventing sheet bonded to and entirely covering the other  
surface of the semiconductor chip, wherein

end surfaces of the warp preventing sheet are flush with corresponding  
end surfaces of the semiconductor chip, wherein a base of the warp preventing sheet is  
made of material identical with that of a base of the substrate.

Claim 5 (Currently Amended): A semiconductor device, ~~according to claim 1,~~  
comprising:

a substrate;  
a semiconductor chip having one surface bonded to a surface of the  
substrate; and

a warp preventing sheet bonded to and entirely covering the other  
surface of the semiconductor chip, wherein

end surfaces of the warp preventing sheet are flush with corresponding  
end surfaces of the semiconductor chip, wherein a base of each of the substrate and  
the warp preventing sheet is a polyimide resin.

Claim 6 (Currently Amended): A semiconductor device according to Claim 4 4,  
wherein the warp preventing sheet has a thickness substantially equal to that of the  
substrate.

Claim 7 (Currently Amended): A semiconductor device according to Claim 4 4,  
wherein the semiconductor device is a thin semiconductor device of a chip-size  
package type.

Claim 8 (Previously Presented): A semiconductor device comprising:  
a substrate;  
a semiconductor chip having one surface bonded to a surface of the  
substrate; and  
a warp preventing sheet bonded to the other surface of the semiconductor  
chip, wherein  
the substrate and the warp preventing sheet are fabricated from different  
materials and a substrate thickness of the substrate and a warp preventing sheet  
thickness of the warp preventing sheet are different from each other yet respective  
ones of at least one of the coefficients of elasticity and coefficients of thermal  
expansion are equal to each other.

Claim 9 (New): A semiconductor device according to Claim 2, wherein the semiconductor device is a thin semiconductor device of a chip-size package type.

Claim 10 (New): A semiconductor device according to Claim 3, wherein the semiconductor device is a thin semiconductor device of a chip-size package type.

Claim 11 (New): A semiconductor device according to Claim 5, wherein the semiconductor device is a thin semiconductor device of a chip-size package type.

## REMARKS

The Examiner's Action mailed on July 16, 2003, has been received and its contents carefully considered.

In this Amendment, Applicant has editorially amended the specification, Figure 1, and claims 2-7. Claim 1 has been canceled. Claims 9-11 have been added. Claims 2, 3, 4, 5 and 8 are the independent claims. Claims 2-11 are pending in the application. For at least the following reasons, it is submitted that this application is in condition for allowance.

It is noted that this Amendment increases the total number of independent claims pending in the application to a total of five (5), thus requiring an excess claim fee of \$172.00 for two independent claims in excess of three (3). A check in this amount is attached. Should additional fees be required, or should the check be inadvertently missing, please charge any necessary fees to Deposit Account No. 18-0002, and advise the undersigned counsel accordingly.

Initially, the Examiner's attention is respectfully directed to the fact that a change in the correspondence address as well as in the Power of Attorney was filed on June 3, 2003. The Examiner's cooperation in directing all future correspondence to the undersigned counsel's address would be appreciated.

The Examiner has objected to the drawings for not illustrating the features of claim 8. In response thereto, Figure 1 has been amended to illustrate the warp preventing sheet 3 having a thickness that is less than the substrate, as well having a thickness that is greater than the substrate. The changes are indicated in red ink. Additionally attached to this Amendment is a revised formal drawing, which includes

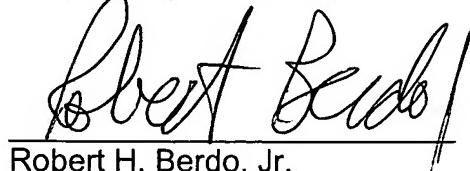
these changes. It is submitted that the drawings comply with all official requirements, and it is requested that this objection be withdrawn.

The Examiner has rejected claim 8 under 35 USC §112 first paragraph, as failing to comply with the written description requirement. However, the Examiner's attention is respectfully directed to page 6, line 18 through page 7, line 14, where it is specifically disclosed that the substrate 1 and the warp preventing sheet 3 can be made of different materials, and can have different thicknesses from each other. Since claim 8 is supported by the original disclosure, it is submitted that claim 8 complies with all official provisions, and it is thus requested that this rejection be withdrawn.

It is noted with great appreciation that the Examiner considers the subject matter of claims 2-5 as being allowable over the art of record. In response thereto, claim 1 has been canceled, and the subject matter recited therein has been incorporated into claims 2-5. Moreover, rejected claims 6 and 7 have been amended to depend from allowable independent claim 4. Thus, all of the Examiner's prior art rejections have been rendered moot, and all of the claims are now in condition for allowance. Such action and the passing of this case to issue are requested.

Should the Examiner feel that a conference would help to expedite the prosecution of the application, the Examiner is hereby invited to contact the undersigned counsel to arrange for such an interview.

Respectfully submitted,



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AMENDMENT

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FIG. 1

